


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST25R3911B-AQFT	AK1Y*TT3911C	A	996G	2017-09-14
	Amount	UoM	Unit type	ST ECOPACK Grade
	65.60	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	5x5x1	32	No lead	
Comment	Package: B01Y VFQFPN 5X5 32L PAD 3.5X3 PUNCHED DM00315111			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	AK1Y*TT3911C				6000001.0	999999.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	4.447	mg	supplier	die	Silicon (Si)	7440-21-3		4.252	mg	956150	64817
Die or dies				supplier	metallization	Aluminium (Al)	7429-90-5		0.014	mg	3148	213
Die or dies				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	1799	122
Die or dies				supplier	metallization	Tungsten (W)	7440-33-7		0.049	mg	11019	747
Die or dies				supplier	Passivation	Silicon Nitride	12033-89-5		0.010	mg	2249	152
Die or dies				supplier	Passivation	Silicon Oxide	7631-86-9		0.114	mg	25635	1738
Bond Wire	M-011 Other inorganic materials	0.090	mg	supplier	Bond Wire	Copper	7440-50-8		0.088	mg	978500	1336
Bond Wire				supplier	Bond Wire	Palladium	7440-05-03		0.002	mg	21500	29
Encapsulation	M-011 Other inorganic materials	27.577	mg	supplier	Mold compound	Silica Fused	60676-86-0		25.561	mg	926892	389642
Encapsulation				supplier	Mold compound	Epoxy Resin	Proprietary		1.390	mg	50420	21195
Encapsulation				supplier	Mold compound	Phenol Resin	Proprietary		0.556	mg	20168	8478
Encapsulation				supplier	Mold compound	Carbon Black	1333-86-4		0.070	mg	2521	1060
Leadframe	M-011 Other inorganic materials	31.437	mg	supplier	Alloy	Iron	7439-89-6		0.687	mg	21865	10478
Leadframe				supplier	Alloy	Phosphorus	7723-14-0		0.023	mg	730	350
Leadframe				supplier	Alloy	Zinc	7440-66-6		0.035	mg	1125	539
Leadframe				supplier	Alloy	Copper	7440-50-8		28.709	mg	913235	437643
Leadframe				supplier	Alloy	Silver	7440-22-4		1.981	mg	63000	30191
Leadframe				JIG - R	Alloy	Lead	7439-92-1		0.001	mg	45	22
Die Attach_EN4900GC	M-011 Other inorganic materials	0.765	mg	supplier	Die Attach	Acrylic resin	65983-31-5		0.046	mg	60000	700
Die Attach_EN4900GC				supplier	Die Attach	Polybutadiene derivative	Proprietary		0.038	mg	50000	583
Die Attach_EN4900GC				supplier	Die Attach	Butadiene copolymer	68891-50-9		0.008	mg	10000	117
Die Attach_EN4900GC				supplier	Die Attach	Epoxy resin	65983-31-5		0.015	mg	20000	233
Die Attach_EN4900GC				supplier	Die Attach	Acrylate	Proprietary		0.031	mg	40000	466
Die Attach_EN4900GC				supplier	Die Attach	Peroxide	3006-86-8		0.004	mg	5000	58
Die Attach_EN4900GC				supplier	Die Attach	Additive	Proprietary		0.008	mg	10000	117
Die Attach_EN4900GC				supplier	Die Attach	Silver (Metal powder)	7440-22-4		0.616	mg	805000	9388
Finishing	M-011 Other inorganic materials	1.285	mg	supplier	Connection coating	Sn	7440-31-5		1.285	mg	1000000	19585